

	! " #	\$! % & '	! () % * +	, -	. /
A	2018-10-19		0 1 - 2	3 4 5	
B	2021-6-7	4/7	6 7 8 9 : ; < b 8 9 = > ? @ A B C D : = > ? E F G H 5 I 50000 J K L M N 7 I 70000 J O 340X340X40、350X350X230 M N 336X336X40、380X335X366	P Q	R 4 S

描述 / Descriptions

T U V F W A X Y Z O [\] ^ _ 2000 V O ` \] A _ 1.0 A O S M A a F b

Surface Mount General Purpose Silicon Rectifiers, Reverse Voltage_ 2000V,Forward

Current:1.0A ,SMA package.

特征 / Features

c d e f g h O i j k l m n RoHS o p 2011/65/EU O q r T U V F b i s t u b

Glass Passivated Chip Junction, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. HF product.

用途 / Applications

v w r x.

General purpose.

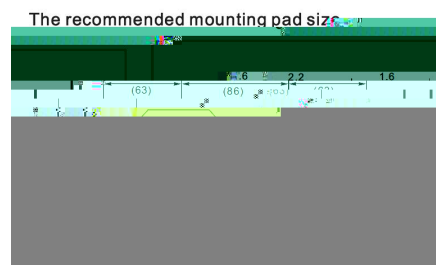
内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN	DESCRIPTION
1	GTU - 15-003



印章代码 / Marking

y z { | } b See Marking Instructions.

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	2000	V
Maximum Average Forward Rectified Current at $T_C = 100\text{ }^{\circ}\text{C}$	$I_F (AV)$	1.0	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load(JEDEC Method)	I_{FSM}	30	A
Typical Junction Capacitance ¹⁾	C_j	20	pF
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	95	$^{\circ}\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55~+150	$^{\circ}\text{C}$

Note:

- 1) Measured at 1 MHz and applied reverse voltage of 4 V D.C
- 2) P.C.B. mounted with 0.2 X 0.2" (5 X 5 mm) copper pad areas.

参数	符号	测试条件
Parameter	Symbol	Test

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Forward Current Derating Curve



Fig.2 Typical Reverse Characteristics

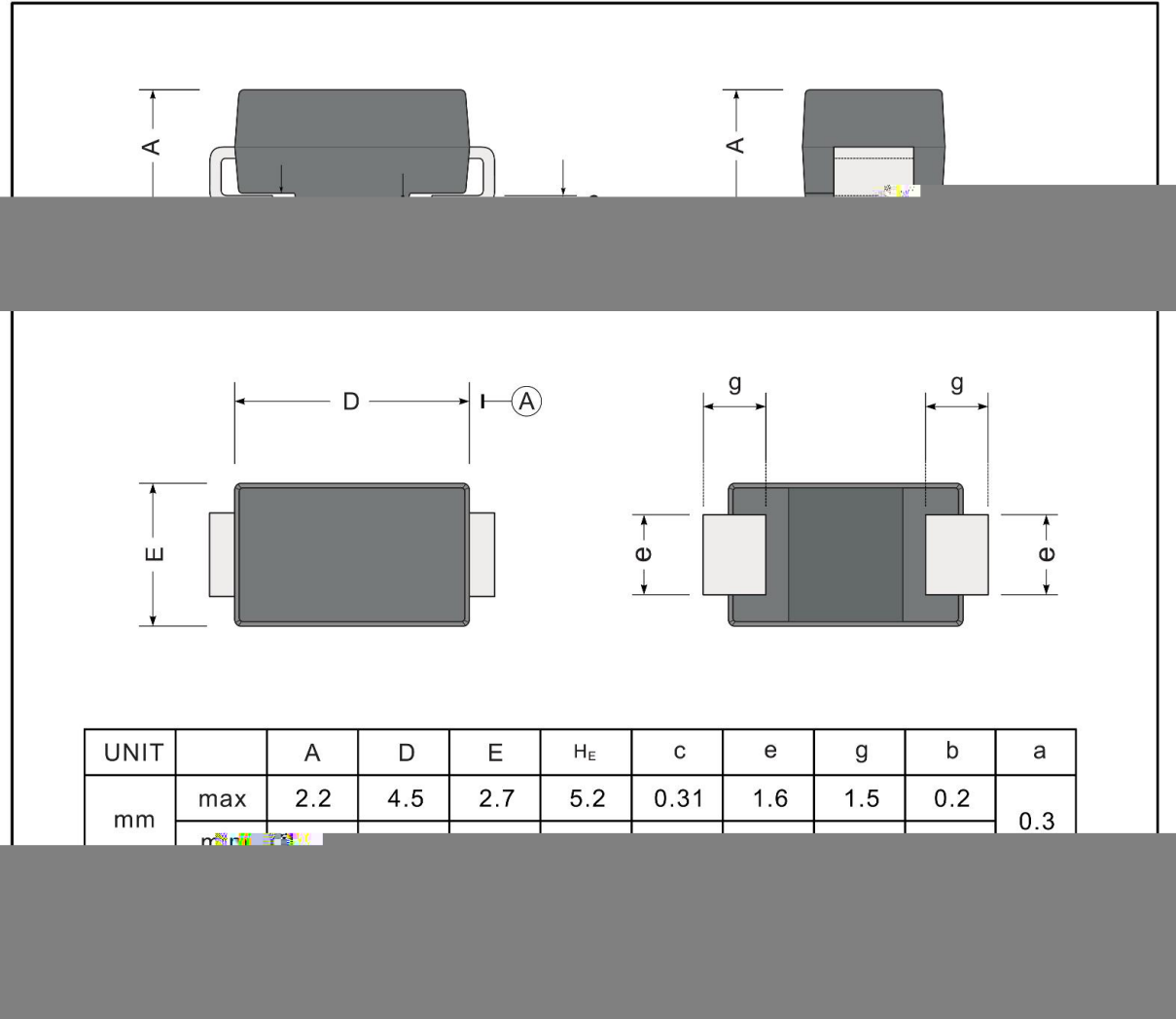


1.2
pulse with 300ms

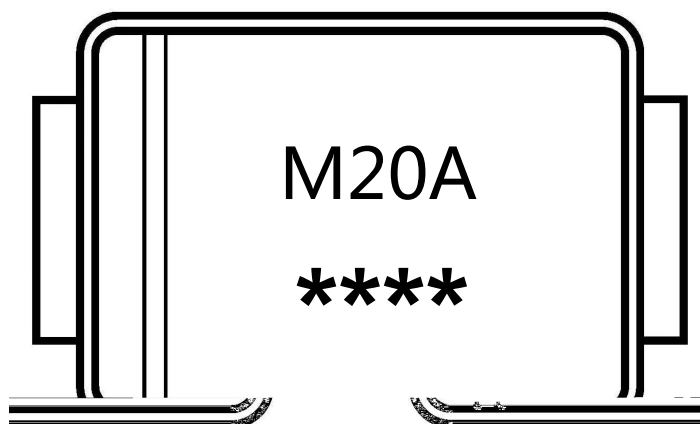
100
100

外形尺寸图 / Package Dimensions

SMA



印章说明 / Marking Instructions



M20A

1 *

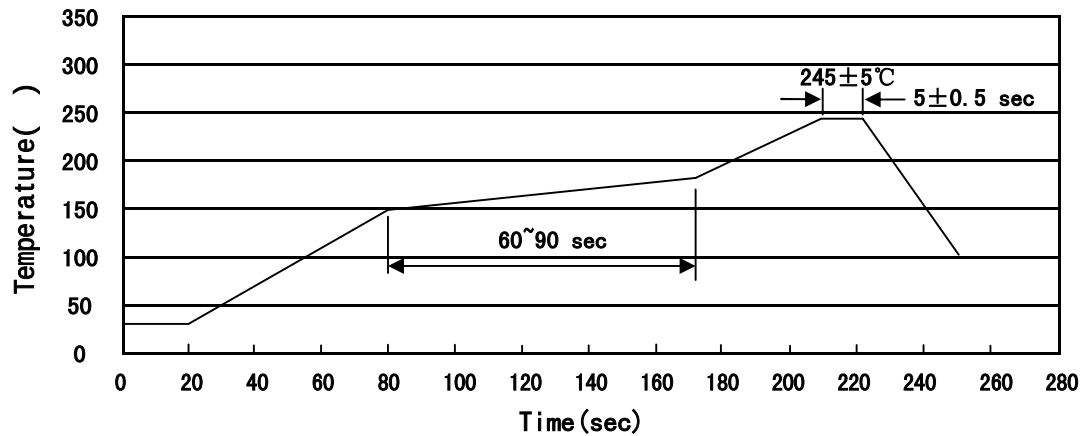
3 *

Note:

M20A Product Type Code

***** Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot No
Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | |
|---|-------------|-----------|--|
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | 5±0.5sec; | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | 2 10°C/sec. | | 3. Cooling Speed: 2~10°C/sec. |

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

260±5°C 10±1 sec. Temp.:260±5°C Time:10±1 sec

包装规格 / Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱
SMA	5000	2	10000	7	70000	13" ×12	336X336X40	380X335X366

使用说明 / Notices